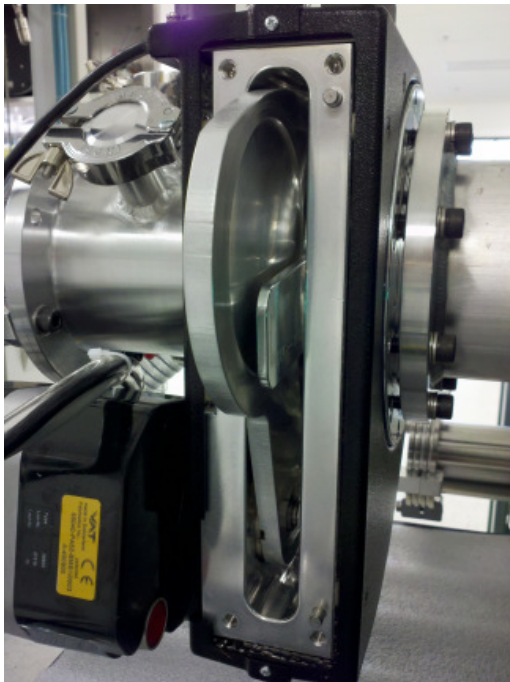
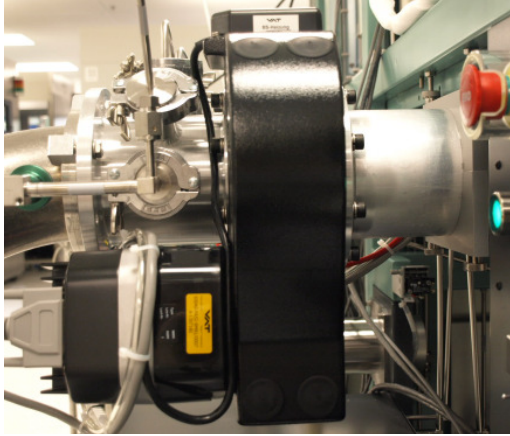


Heated Pendulum Valve



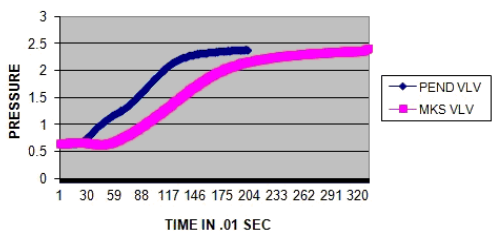
Concept Part Solutions is working to extend the lifetime of today's aging semiconductor manufacturing equipment. Component obsolescence and reliability are driving suppliers to provide innovative improvement upgrades to meet these demands. The C1 Heated Pendulum Valve is a system enhancement that will provide greater reliability and extendability for the Concept One System platform.

The C1 platform uses the combination of a TYLAN throttle valve and VAT gate valve for pressure control. The Throttle Valve controller in the current configuration is now obsolete driving the need for an option to extend system lifetime. The Heated Pendulum Valve is a dual purpose component that replaces the current two Valve configuration with one, easy to maintain unit. The Pendulum valve has a built in heater circuit to maintain the valve at 120 degrees C. The Pendulum Valve enhancement uses Kalrez o-rings to maximize the number of wafers that can be processed before the unit requires a PM resulting in improved MTBF. Process results show faster pressure control from wafer transfer to process steps. Process results are transparent; there is no change to process performance or particle data. The normal PM of the valve can be completed in less than 30 minutes since only the slider plate needs to be removed. The Heated Pendulum Valve is available for both the external and internal valving configurations.

Upgrade Benefits

- Simplified design is more reliable than current configuration improving reliability - Up to 2X MTBF improvement over current throttle valve and gate valve combination
- Integrated heater reduces by product build up on systems that do not have Throttle and Gate Valve Heater
- Pendulum Valve Cost is 40% less than the 2 valves which reduces long term cost; eliminates need to stock multiple parts
- Decreased PM Frequency - Gate Valve & Throttle Valve are PM'ed every 120K wafers Vs 240K wafers for the Pendulum Valve
- Time to PM reduced from 2 hours to 30 minutes
- Fully tested, process transparent obsolescence replacement option for aging equipment components

PEND VS MKS TO 2.4 TORR



Heated Pendulum Valve

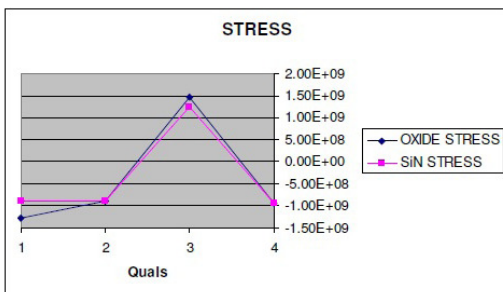
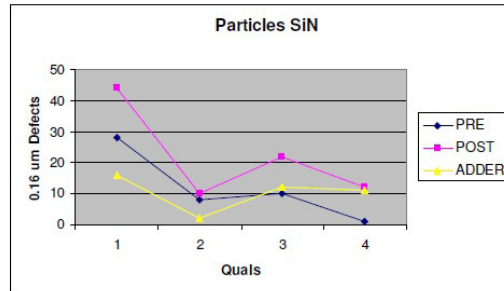
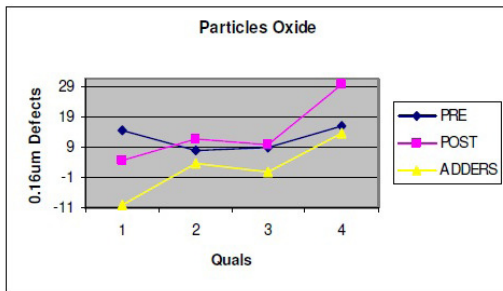
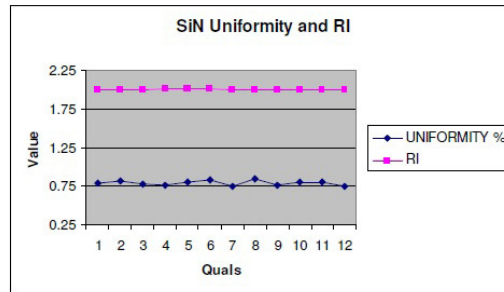
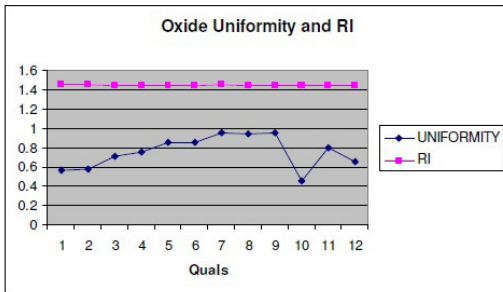
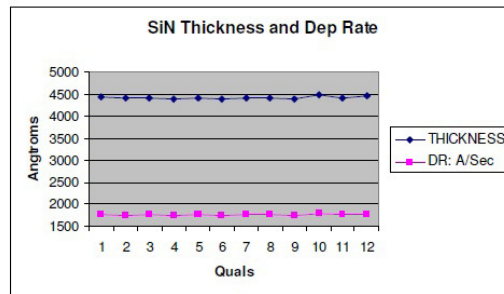
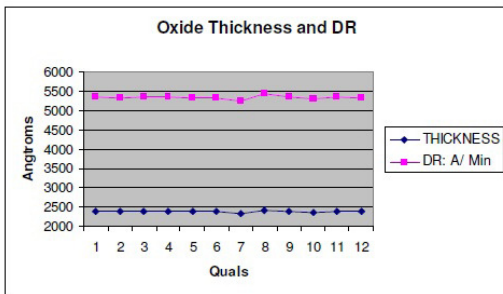


Process transparency data from Beta site showing wafer thickness, stress, uniformity, and RI

Oxide Recipe is Standard Novellus at 2.4 K thickness.

SiN Recipe is Standard Novellus at 4.5 K Thickness.

Defects measured using SP 1.



Beta Test Data provided by Novellus Field Process group using standard Novellus BKM Process Test Parameters